JAYPEE UNIVERSITY OF INFORMATION TECHNOLOGY, WAKNAGHAT TEST-2 EXAMINATION- APRIL -2018 B.Tech VI Semester

COURSE CODE: 10B11EC612

MAX. MARKS: 25

COURSE NAME: VLSI TECHNOLOGY AND APPLICATIONS

COURSE CREDITS: 04

MAX. TIME: 1 HRS 30 MIN

Note: All questions are compulsory. Carrying of mobile phone during examinations will be treated as case of unfair means.

1.

(CO1, CQ4) $[4 \times 5 = 5]$

- (a) How noise sensitivity is different from noise immunity?
- (b) Draw and explain the high frequency model of a MOSFET.
- (c) A slow circuit dissipates less power than a fast circuit. Justify.
- (d) Threshold voltage of a MOSFET is -1.35V. Which all MOSFET's satisfy this specification? Draw symbols.
- (e) A depletion type *n*-channel MOSFET is biased in its linear region for use as a voltage controlled resistor. Assume $V_{\rm th} = 0.5 {\rm V}$, $V_{\rm GS} = 2 {\rm V}$, $V_{\rm DS} = 5 {\rm V}$, W/L = 100, $C_{\rm ox} = 10^{-8} {\rm F/cm^2}$ and $\mu_{\rm n} = 800 {\rm cm^2/V}$ -sec. The value of the resistance of the voltage controlled resistor (in m Ω) is ______

2.

(CO1, CO3) [3+3=6]

(a) Consider n-MOS transistor with source and body connected together. Calculate the threshold voltage (in volts) of the transistor assuming that the electron mobility is dependent of $V_{\rm GS}$ and $V_{\rm DS}$. Given: $g_{\rm m}=0.5\mu{\rm A/V}$ for $V_{\rm DS}=50{\rm mV}$ and $V_{\rm GS}=2{\rm V}$. $g_{\rm d}=8~\mu{\rm A/V}$ for $V_{\rm GS}=2{\rm V}$ and $V_{\rm DS}=0{\rm V}$.

where
$$g_m = \frac{\partial I_D}{\partial V_{OS}}$$
 and $g_d = \frac{\partial I_D}{\partial V_{DS}}$

- (b) Calculate the parasitic drain capacitance for *n*-MOS transistor operating at $W = 5 \mu \text{m}$, $L = 0.5 \mu \text{m}$, $Y = 3 \mu \text{m}$, $\phi_0 = 0.7 \text{V}$, $\phi_{0\text{sw}} = 0.9 \text{V}$ $C_{\text{sb0}} = 0.86 \text{ fF}/\mu \text{m}^2$, $C_{\text{db0}} = 0.24 \text{ fF}/\mu \text{m}^2$, $C_{\text{sbsw}} = 0.24 \text{ fF}/\mu \text{m}$, $C_{\text{dbsw}} = 0.24 \text{ fF}/\mu \text{m}$, $C_{\text{msw}} = 0.36$, $C_{\text{msw}} = 0.4 \text{ and reverse bias voltage 3V}$.
- Design Linear RC model of an *n*-channel MOS transistor having parameters: substrate doping density = 10^{16} /cm³, polysilicon gate doping density = 2×10^{20} /cm³, $N_{A(chanstop)} = 10^{19}$ / cm³, gate oxide thickness = 50nm, oxide interface fixed charge density = 4×10^{10} /cm², abrupt junction depth = $0.4 \mu m$, length of drain = $9 \mu m$, width = $4 \mu m$, length of channel = $1.5 \mu m$, drain to bulk voltage = 1.5 V, gate to source voltage = 1.5 V, drain to source voltage = 1.5 V, threshold voltage = 0.8 V, electron mobility = $6.50 \text{ cm}^2/V$ -s. Assume diffusion capacitance.

4.

(CO4) $[2 \times 4 = 8]$

- (a) Design a resistive load inverter with $R=1~\mathrm{k}\Omega$, such that $V_{\mathrm{OL}}=1\mathrm{V}$. The enhancement type nMOS driver transistor has the following parameters: $\mu_{\mathrm{n}}C_{\mathrm{ox}}=22~\mu\mathrm{A/V}^2$, $V_{\mathrm{TO}}=1\mathrm{V}$, $V_{\mathrm{DD}}=4.0\mathrm{V}$. Determine the required aspect ratio. Determine input low voltage parameter.
- (b) Draw the VTC curve for resistive load *n*-MOS inverter. Determine the $V_{\rm OH}$ and $V_{\rm OL}$ when biased at $V_{\rm DD} = 2.5 \, \rm V$, $k' = 1 \, \mu A/V^2$, $V_{\rm 10D} = 0.5 \, \rm V$, $(W/L)_D = 10$, $R = 2 \, \rm K\Omega$.